Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.125”**

**.107”**

**ANODE**

**Top Material: Al**

**Backside Material: TiNiAg**

**Bond Pad Size: .107”**

**Backside Potential: CATHODE**

**Mask Ref: SENS3126**

**APPROVED BY: DK DIE SIZE .107” X .125” DATE: 11/10/21**

**MFG: SENSITRON THICKNESS .010” P/N: 1N6282**

**DG 10.1.2**

#### Rev B, 7/1